



## Material Content Data Sheet



<b>Sales Product Name</b>		IDH10S120		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA000622910						
<b>Package</b>		PG-TO220-2-1		<b>Weight*</b>		1973.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.030	0.25	0.25	2548	2548
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		381	
	inorganic material	phosphorus	7723-14-0	0.226	0.01		114	
	non noble metal	copper	7440-50-8	751.797	38.09	38.14	380875	381371
wire	non noble metal	aluminium	7429-90-5	1.289	0.07	0.07	653	653
encapsulation	organic material	carbon black	1333-86-4	9.020	0.46		4570	
	plastics	epoxy resin	-	99.215	5.03		50265	
	inorganic material	silicondioxide	60676-86-0	493.070	24.98	30.47	249800	304635
leadfinish	non noble metal	tin	7440-31-5	14.668	0.74	0.74	7431	7431
plating	non noble metal	nickel	7440-02-0	0.198	0.01		100	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	1	100
solder	noble metal	silver	7440-22-4	0.209	0.01		106	
	non noble metal	tin	7440-31-5	0.167	0.01		85	
	non noble metal	lead	7439-92-1	7.988	0.40	0.42	4047	4238
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		299	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		90	
	non noble metal	copper	7440-50-8	589.466	29.86	29.90	298635	299024
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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